Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.091”**

**.075”**

**ANODE**

**TOP**

**BACK**

**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size: .0069” min .0075” max**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .087” min X .091” max DATE: 3/28/17**

**MFG: SENSITRON THICKNESS .000” P/N: 1N4974**

**DG 10.1.2**

#### Rev B, 7/1